

RX1 Series Picosecond Lasers

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Photonics Industries' RX1 Series low power picosecond lasers offer high performance, high precision, and robust form factor for the most demanding industrial as well as scientific applications. Photonics Industries is proven, with over a thousand picosecond lasers shipped worldwide, to meet and fulfill precision needs in manufacturing, scientific research, and new, emerging requirements necessitating ever smaller pulse widths in the ultrafast regime.



 Applications Cutting/Drilling/Scribing Thin Metal/Metal Foil, Ceramic, Glass, Ultra Thin Glass (UTG), Plastic, Glass-reinforced Plastic Flat Panel Display, LCD/LED/OLED Repair/Microprocessing Ink-Jet Nozzle Hole Drilling, Laser Milling Ink-Jet Nozzle Holes, Laser Ablation Ink-Jet Nozzle Holes, Laser Ablation Ink-Jet Nozzle Holes, Laser Microprocessing Low-k Dielectric Wafers, Silicon Wafers, Flexible Printed Circuit Boards (PCB), Microprocessing Hydropholic Material Manufacturing, Hydropholic Material Manufacturing, Ultrafast Laser Assisted Etching (ULAE) Systems Features Short pulse laser: ~10 ps for IR, ~7 ps for Green & UV Option up to ~50 ps available Wide range of wavelengths: 1064 nm, 532 nm, 355 nm MWB, MWS, & 266 nm options on request Smallest, all-in-one (AIO), high power picosecond on the market High repetition rates: Up to 8 MHz Excellent TEM00 beam, and Pointing Stability: Typical M² < 1.2; < 20 µrad Exceptional and Versatile Pulse Control: PEC (Power or Pulse Energy Control) PSO (Position Synchronized Output) support f external triggering to any arbitrary PRF while maintaining a constant, stable pulse energy w jitter Burst Mode for individually controllable bursts 10 pulses with a separation of 14 ns POD (Pulse-On-Demand) pulse bursts can be 		
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Specifications - RX1 Series Picosecond Lasers, Low Power IR Models

IR Models	RX1-1064-10	RX1-1064-30	RX1-1064-40				
Beam and output specifications							
Wavelength	1064 nm						
Average power	10 W at 2 MHz	30 W at 2 MHz	40 W at 2 MHz				
Pulse width	~10 ps						
Pulse repetition rate ¹	Sin	Single shot to 2 MHz (option up to 8 MHz)					
Pulse-to-pulse stability ²	~1% rms						
Long term power stability ³	≤ 1% rms						
Beam diameter, at exit		~1.5 mm					
Beam spatial mode	TEM ₀₀ M ² ~1.2						
Beam pointing stability	< 20 µrad						
Beam divergence	< 2 mrad						
Beam roundness	> 90%						
Beam bore sight	≤ 1 mm lateral (to specified exit location) ≤ 5 mrad angular (to specified exit direction)						
accuracy	\leq 1 min lateral (to specified exit location), \leq 5 million angular (to specified exit difection)						
Operational specifications and system characteristics							
Interface	RS232, Ethernet, Software GUI, External TTL Triggering						
Warm-up time	< 15 minutes						
Electrical requirement	100-240 V AC; or 32 V DC, 10 A						
Line frequency	50-60 Hz						
Climate	Ambient 15°C to 30°C (59°F to 86°F) Operating Range,						
	Relative Humidity 90% Maximum, non-condensing						
Power consumption ⁴	< 400 W						
Dimensions (LxWxH) ⁵	21 x 8.5 x 3.75 in.						
Weight	~50 lbs						
Vibrational tolerance	Up to 3g						
Cooling system ⁶	Closed-loop chiller						

1. Lower repetition rates, down to single shot, achieved by utilizing PSO or POD features. 2. Measured at a pulse repetition rate of 1 MHz, and at an ambient temperature of \pm 2°C.

3. Measured over 8 hours \pm 1°C.

 Power consumption data does not include an external chiller's power consumption.
 RX Series picosecond lasers are all-in-one (AIO) and do not require a separate controller or utility module. All connections for operation and control of the laser can be found on the back panel of the AIO laser.

6. Air-cooled option available for low power RX Series models. Contact us.



Average power (W) as a function of



Specifications - RX1 Series Picosecond Lasers, Low Power GRN Models

GRN Models		RX1-532-5 RX1-532-20 RX1-532-25				
Beam and output specifications						
Wavelength		532 nm				
Average power	-L	5 W at 200 kHz	20 W at 200 kHz	25 W at 200 kHz		
	-M	5 W at 400 kHz	20 W at 400 kHz	25 W at 400 kHz		
	-H	5 W at 1 MHz	20 W at 1 MHz	25 W at 1 MHz		
Pulse width			~7 ps			
Pulse repetition rate	1	Sin	Single shot to 2 MHz (option up to 8 MHz)			
Pulse-to-pulse stabil	ity ²		~1% rms			
Long term power stability ³			≤ 1% rms			
Beam diameter, at e	exit	~1 mm ~1.5 mm				
Beam spatial mode		$TEM_{00} M^2 < 1.2$				
Beam pointing stabil	lity	< 20 µrad				
Beam divergence		≤ 1 mrad				
Beam roundness		> 90%				
Beam bore sight		< 1 mm lateral (to specified exit location) < 5 mrad angular (to specified exit direction)				
accuracy		\leq 1 mm lateral (to specified exit location), \leq 5 mrad angular (to specified exit direction)				
Operational specif	icatio	ons and system characteristics				
Interface		RS232, Ethernet, Software GUI, External TTL Triggering				
Warm-up time		< 15 minutes				
Electrical requirement	nt	100-240 V AC; or 32 V DC, 10 A				
Line frequency		50-60 Hz				
Climate		Ambient 15°C to 30°C (59°F to 86°F) Operating Range,				
		Relative Humidity 90% Maximum, non-condensing				
Power consumption ⁴		< 400 W				
Dimensions (LxWxH)5	21 x 8.5 x 3.75 in.				
Weight		~50 lbs				
Vibrational tolerance	è	Up to 3g				
Cooling system ⁶		Closed-loop chiller				

1. Lower repetition rates, down to single shot, achieved by utilizing PSO or POD features. 2. Measured at a pulse repetition rate of 1 MHz, and at an ambient temperature of \pm 2°C. 3. Measured over 8 hours \pm 1°C.

4. Power consumption data does not include an external chiller's power consumption.

5. RX Series picosecond lasers are all-in-one (AIO) and do not require a separate controller or utility module. All connections for operation and

control of the laser can be found on the back panel of the AIO laser. 6. Air-cooled option available for low power RX Series models. Contact us.



Specifications - RX1 Series Picosecond Lasers, Low Power UV Models

UV Models		RX1-355-3 RX1-355-10 RX1-355-15				
Beam and output specifications						
Wavelength		355 nm				
Average power	-L	3 W at 200 kHz	10 W at 200 kHz	15 W at 200 kHz		
	-M	3 W at 400 kHz	10 W at 400 kHz	15 W at 400 kHz		
	-H	3 W at 1 MHz	10 W at 1 MHz	15 W at 1 MHz		
Pulse width			~7 ps			
Pulse repetition rate	L	Sin	gle shot to 2 MHz (option up to 8 MI	Hz)		
Pulse-to-pulse stabili	ity ²		< 2% rms			
Long term power stability ³			≤ 1% rms			
Beam diameter ⁴ , at e	exit	~0.75 mm ~1 mm				
Beam spatial mode		$TEM_{00} M^2 < 1.2$				
Beam pointing stabil	ity	< 25 µrad				
Beam divergence		≤ 1 mrad				
Beam roundness		> 90%				
Beam bore sight		< 1 mm lateral (to specified exit location) < 5 mrad angular (to specified exit direction)				
accuracy		\leq 1 min lateral (to specified exit location), \leq 5 mrad angular (to specified exit direction)				
Operational specif	icatio	ns and system characteristics				
Interface		RS232, Ethernet, Software GUI, External TTL Triggering				
Warm-up time		< 15 minutes				
Electrical requirement	nt	100-240 V AC; or 32 V DC, 10 A				
Line frequency		50-60 Hz				
Climate		Ambient 15°C to 30°C (59°F to 86°F) Operating Range,				
		Relative Humidity 90% Maximum, non-condensing				
Power consumption ⁵		< 400 W				
Dimensions (LxWxH)	6	21 x 8.5 x 3.75 in.				
Weight		~50 lbs				
Vibrational tolerance		Up to 3g				
Cooling system ⁷		Closed-loop chiller				

1. Lower repetition rates, down to single shot, achieved by utilizing PSO or POD features. 2. Measured at a pulse repetition rate of 1 MHz, and at an ambient temperature of \pm 2°C. 3. Measured over 8 hours \pm 1°C.

4. Expanded beam diameters (~4 mm) are available. Contact us.

5. Power consumption data does not include an external chiller's power consumption.

6. RX Series picosecond lasers are all-in-one (AIO) and do not require a separate controller or utility module. All connections for operation and control of the laser can be found on the back panel of the AIO laser.

7. Air-cooled option is available for low power RX Series models. Contact us.





Dimensional Drawing



Photonics Industries RX Series picosecond lasers are all-inone (AIO) and do not require a separate controller or utility module. All connections for operation and control of the laser can be found on the back panel of the AIO laser.

Due to Photonics Industries' commitment to continuous product improvement, specifications and drawings are subject to change without notice.

Photonics Industries conforms to provisions of US 21 CFR 1040.10 & 1040.11 and is made under one or more US patents listed below: 9,531,147, 8,817,831, 7,869,471, 7,346,092, 7,082,149, 7,079,557, 6,999,483, 6,980,574, 6,961,355, 6,842,293, 6,762,405, 6,690,692, 6,587,487, 6,584,134, 6,366,596, 6,356,578, 6,327,281, 6,246,707, 6,229,829, 6,108,356, 6,061,370, 6,028,620, 5,395,6383, 5,898,717 and Pending Patents.

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Photonics Industries International is the pioneer of intracavity harmonic lasers and is at the forefront of developing, manufacturing and marketing a wide range of nanosecond, sub-nanosecond, picosecond and femtosecond lasers for industrial, scientific, defense, and medical industries. Check out our products and see how we can help you apply our lasers to your needs.



Photonics Industries